## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2568801

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Ching-Wen Hung	09/05/2013
Jia-Rong Wu	09/05/2013
Chih-Sen Huang	09/05/2013
Chieh-Te Chen	09/05/2013

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City:	Hsin-Chu City
State/Country:	TAIWAN

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14048043

### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	SHELLEY KUO
Signature:	/SHELLEY KUO/
Date:	10/08/2013 <b>PATENT</b>

502523611 REEL: 031359 FRAME: 0112

Total Attachments: 8	
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PATENT REEL: 031359 FRAME: 0113

## Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or	r			
☐ United States application nu	ımber	file	d on	, or
☐ PCT international applicatio	n number		filed on	
The above-identified application was	made or authorized t	o be made by m	ie.	
I believe that I am the original invent application.	or or an original joint i	nventor of a clai	med invention i	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement mad isonment of not more	e in this declara than five (5) yea	tion is punishab ırs, or both.	le
In consideration of the payment by	UNITED MICROE CORP.	LECTRONICS	having a po	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-C	hu City 300,	Taiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One I nd valuable considerat	Oollar (\$ 1.00), ti ion.	he receipt of wh	ich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all impro tion and, in and to, all r any continuations, co	ovements which Letters Patent to Intinuation-in-pa	are disclosed ir o be obtained fo rt, divisions, rer	n the or said newals,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or n this assignment;	encumbrance h	as been or will l	be made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters I estify as to the same in	Patent and legal any interferenc	equivalents as e, litigation prod	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention cessary or desirable t	n and said Letter o carry out the p	s Patent and sa	aid f. _(Date of signing) _
Notes An annihation data about CDTC	2/02/44			

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor</u>.

Page 1 of 8

NPO#NAU-P1989-USA:0 CUST#UMCD-2013-0182

LÉGAL NAMÉ OF INVENTOR(ASSIGNOR)

Inventor: Ching-Wen Hung

Date: crp

SEP 0 5 2013

Signature

Ching-Wen Hung

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F#NPO-P0002E-US1201 DSC0-102U008784

NPO#NAU-P1989-USA:0 CUST#UMCD-2013-0182

PATENT ———— REEL: 031359 FRAME: 0115

Title of In	venti	on:					
METHOD	<b>FOR</b>	<b>FABRICAT</b>	NG SEA	<b>MICONDU</b>	CTOR	DEVIC	`F

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or	•			
☐ United States application nu	ımber	filed	on	, or
☐ PCT international applicatio	n number	file	ed on	
The above-identified application was	made or authorized to be	made by me.		
I believe that I am the original invent application.	or or an original joint inver	ntor of a claime	ed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in isonment of not more than	this declaration five (5) years	n is punishable , or both.	
In consideration of the payment by	UNITED MICROELEC	CTRONICS	having a postal a	iddress of
No.3, Li-Hsin Road 2, Science	-Based Industrial Par	rk, Hsin-Chu	– ı City 300, Taiwa	an, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dolland valuable consideration.	ar (\$ 1.00), the	receipt of which is	hereby
I hereby sell, assign and transfer to the entire right, title and interest in an invention as above-identified application on the substitutes, or extensions thereof, ar	nd to any and all improven tion and, in and to, all Lett r any continuations, contin	nents which ar ters Patent to b uation-in-part,	e disclosed in the be obtained for said divisions, renewals	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or enc n this assignment;	umbrance has	been or will be ma	de or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Pate estify as to the same in any	ent and legal ed / interference,	quivalents as may b litigation proceeding	ре
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and ecessary or desirable to ca	d said Letters l rry out the pro	Patent and said poses thereof.	e of signing)
Note: An application data sheet (PTC inventive entity, must accompany this				

Page 3 of 8

NPO#NAU-P1989-USA:0 CUST#UMCD-2013-0182

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Jia-Rong Wu

Date:

SEP 05 2013

Signature:

Jia-Pong

Wu

Page 4 of 8

F#NPO-P0002E-US1201 DSC0-102U008784

NPO#NAU-P1989-USA:0 CUST#UMCD-2013-0182

REEL: 031359 FRAME: 0117

## Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, o	•			
☐ United States application number		filed	on	, or
☐ PCT international application	n number	file	ed on	
The above-identified application was	s made or authorized to be m	ade by me.		
I believe that I am the original inventapplication.	or or an original joint inventor	of a claime	ed invention i	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				le
In consideration of the payment by	UNITED MICROELECTICORP.	RONICS	having a p	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park,	Hsin-Chւ	 u City 300,	Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are		\$ 1.00), the	receipt of wh	ich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application o substitutes, or extensions thereof, an	nd to any and all improvemen tion and, in and to, all Letters r any continuations, continuat	its which ar Patent to li ion-in-part,	e disclosed in be obtained for divisions, rer	n the or said newals,
I hereby covenant that no assignmentered into which would conflict with	nt, sale, agreement or encum h this assignment;	brance has	been or will l	oe made or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exe	ntion and said Letters Patent a estify as to the same in any in	and legal e terference,	quivalents as litigation prod	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	olication, said invention and secessary or desirable to carry	aid Letters out the pro	Patent and sa	aid f. _(Date of signing
Note: An application data sheet (PT				

Page 5 of 8

NPO#NAU-P1989-USA:0 CUST#UMCD-2013-0182

LËGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chih-Sen Huang

Date:

SEP 05 2013 SEP 05 2013

Signature:

Chih-Sen Huang

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F#NPO-P0002E-US1201 DSC0-102U008784

PATENT REEL: 031359 FRAME: 0119

Title of Invention:	
METHOD FOR FABRICATING SEMICONDUCTOR	DEVICE

As the below named inventor, I here This declaration is directed to:	eby declare that:	•
☑ The attached application, or	r	
☐ United States application no	umber	_filed on, or
☐ PCT international application	on number	filed on
The above-identified application was	s made or authorized to be made	by me.
I believe that I am the original invent application.	tor or an original joint inventor of	a claimed invention in the
l hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	al false statement made in this de risonment of not more than five (	claration is punishable 5) years, or both.
In consideration of the payment by	UNITED MICROELECTRO CORP.	NICS having a postal address of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hs	in-Chu City 300, Taiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1. nd valuable consideration.	00), the receipt of which is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements wation and, in and to, all Letters Pa r any continuations, continuations	vhich are disclosed in the tent to be obtained for said -in-part, divisions, renewals,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbra h this assignment;	nce has been or will be made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said ecessary or desirable to carry out	Letters Patent and said
Note: An application data sheet (PT0 inventive entity, must accompany thi	O/SB/14 or equivalent), including is form. Use this form for each ad	naming the entire

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NPO#NAU-P1989-USA:0 CUST#UMCD-2013-0182

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chieh-Te Chen

Date:

SEP 05 2013

Signature: Chief-Te Cheu

Page 8 of

F#NPO-P0002E-US1201 DSC0-102U008784

**RECORDED: 10/08/2013** 

NPO#NAU-P1989-USA:0

CUST#UMCD-2013-0182

**PATENT REEL: 031359 FRAME: 0121**